Product/Process Change Notice - PCN 13_0248 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: Assembly and Test Transfer of Select 4x4 and 5x5mm LFCSP Products using 8900 Die Attach to STATS ChipPAC China

Publication Date: 14-Jul-2014

Effectivity Date: 18-May-2014 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Include Qualification and Test Correlation Report Summary.

Description Of Change

ADI is transferring to subcontractor STATS ChipPAC China for the assembly and test manufacturing of select 4x4 and 5x5mm LFCSP products using Ablestik 8900 die attach. The package outline dimensions and BOM of each product will be maintained.

Reason For Change

ADI is transferring to STATS ChipPAC China due to the closure of STATS ChipPAC Malaysia at the end of 2014.

ADI's assembly subcontractors manufacture products using Analog Devices specified manufacturing flows, materials, process controls and monitors, ensuring the same level of quality and reliability on products they receive from the new site.

Impact of the change (positive or negative) on fit, form, function & reliability

The transfer will have no impact on the form, fit, function and reliability of the devices.

Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled after the transfer will be identified by assembly lot and the country of origin.

Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Report Summary.
Test correlation and validation is in process. Please see the attached list for the Test Correlation Report Summary for completed parts.

Supporting Documents

Attachment 1: **Type**: Test Correlation Report

ADI_PCN_13_0248_Rev_A_Test Correlation Report 0710.pdf

Attachment 2: **Type**: Detailed Change Description

ADI_PCN_13_0248_Rev_A_BOM.pptx

Attachment 3: Type: Qualification Results Summary
ADI_PCN_13_0248_Rev_A_Qualification Results_Summary.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative					
Americas:	PCN_Americas@analog.com	**Europe:**	PCN_Europe@analog.com	**Japan:**	PCN_Japan@analog.com
				Rest of Asia:	PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Existing Parts - Product Family / Model Number (15)				
ADG5204 / ADG5204BCPZ-RL7	ADG5206 / ADG5206BCPZ-RL7	ADG5207 / ADG5207BCPZ-RL7	ADG5208 / ADG5208BCPZ-RL7	ADG5209 / ADG5209BCPZ-RL7
ADG5212 / ADG5212BCPZ-RL7	ADG5213 / ADG5213BCPZ-RL7	ADG5233 / ADG5233BCPZ-RL7	ADG5236 / ADG5236BCPZ-RL7	ADG5404 / ADG5404BCPZ-REEL7
ADG5408 / ADG5408BCPZ-REEL7	ADG5409 / ADG5409BCPZ-REEL7	ADG5413 / ADG5413BCPZ-REEL7	ADG5433 / ADG5433BCPZ-REEL7	ADG5436 / ADG5436BCPZ-REEL7

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	07-Nov-2013	18-May-2014	Initial Release
Rev. A	14-Jul-2014	18-May-2014	Include Qualification and Test Correlation Report Summary.